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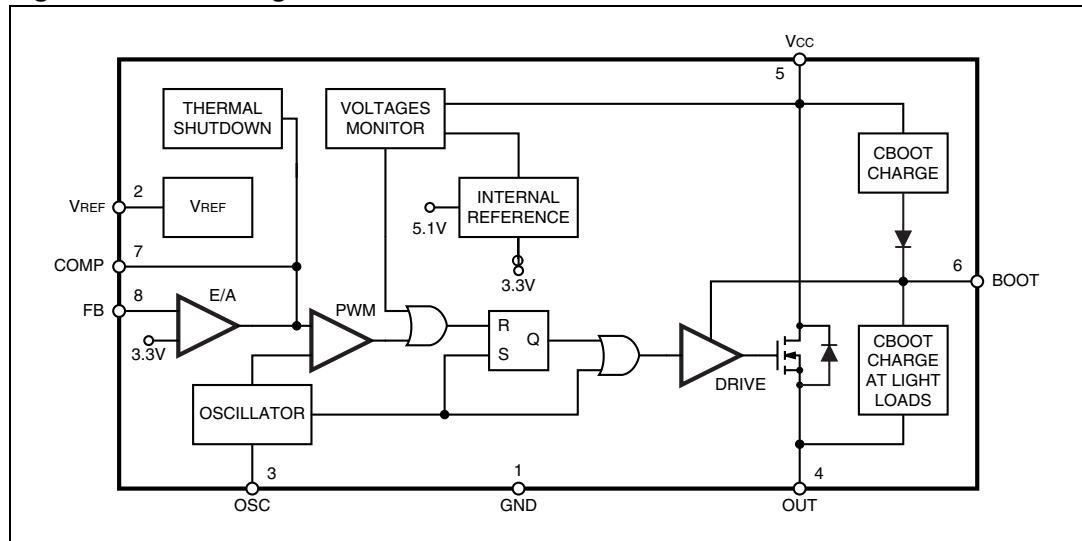
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1 Block diagram

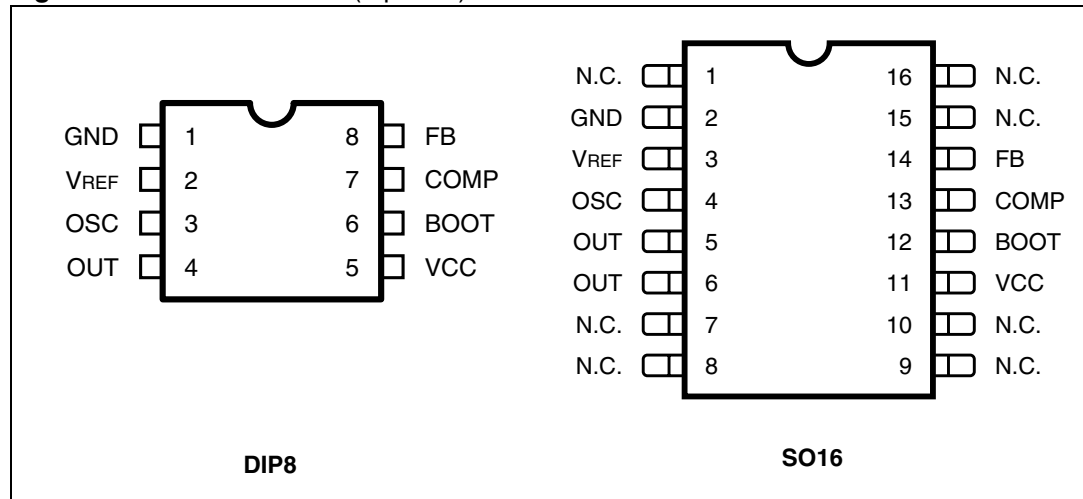
Figure 2. Block diagram



2 Pin settings

2.1 Pin connection

Figure 3. Pin connection (top view)



2.2 Pin description

Table 1. Pin description

N° Pin		Name	Description
DIP8	SO16W ⁽¹⁾		
1	2	GND	Ground
2	3	VREF	5.1V Reference voltage with 20mA current capability.
3	4	OSC	An external resistor connected between the unregulated input voltage and this pin and a capacitor connected from this pin to ground fix the switching frequency. (Line feed forward is automatically obtained)
4	5, 6	OUT	Stepdown regulator output.
5	11	VCC	Unregulated DC input voltage.
6	12	BOOT	A capacitor connected between this pin and OUT allows to drive the internal VDMOS.
7	13	COMP	E/A output to be used for frequency compensation.
8	14	FB	Stepdown feedback input. Connecting directly to this pin results in an output voltage of 3.3V. An external resistive divider is required for higher output voltages.

1. Pins 1, 7, 8, 9, 10, 15 and 16 are not internally, electrically connected to the die.

3 Electrical data

3.1 Maximum ratings

Table 2. Absolute maximum ratings

Symbol		Parameter	Value	Unit	
DIP8	S016W				
V5	V11	Input voltage	58	V	
V4	V5, V6	Output DC voltage	-1	V	
		Output peak voltage at t = 0.1μs, f = 200kHz	-5	V	
I4	I5, I6	Maximum output current	internal limit		
V6-V5	V12-V11		14	V	
V6	V12	Bootstrap voltage	70	V	
V7	V13	Analogs input voltage (V _{CC} = 24V)	12	V	
V8	V14	(V _{CC} = 20V)	6	V	
			-0.3	V	
P _{TOT}		Power dissipation a T _A ≤ 60°C	DIP8	1	W
			SO16	0.8	W
T _J ,T _{STG}		Junction and storage temperature	-40 to 150	°C	

3.2 Thermal data

Table 3. Thermal data

Symbol	Parameter	DIP8	S016W	Unit
R_{thJA}	Maximum thermal resistance junction-ambient	90 ⁽¹⁾	110 ⁽¹⁾	$^\circ\text{C/W}$

1. Package mounted on board

3.3 Operating temperature rating

Table 4. Operating temperature rating

Symbol	Parameter	Value	Unit
T_J	Junction temperature range	-40 to 150	$^\circ\text{C}$

4 Electrical characteristics

Table 5. Electrical characteristics

(T_J = 25°C, C_{OSC} = 2.7nF, R_{OSC} = 20kΩ, V_{CC} = 24V, unless otherwise specified.)

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
Dynamic characteristic						
V _I	Operating input voltage range	V _O = 3.3 to 50V; I _O = 1A ⁽¹⁾	8		55	V
V _O	Output voltage	I _O = 0.5A	3.33	3.36	3.39	V
		I _O = 0.2 to 1A	3.292	3.36	3.427	V
		V _{CC} = 8 to 55V ⁽¹⁾	3.22	3.36	3.5	V
V _d	Dropout voltage	V _{CC} = 10V; I _O = 1A		0.29	0.367	V
		⁽¹⁾			0.587	V
I _l	Maximum limiting current	V _{CC} = 8 to 55V ⁽¹⁾	1.5	2	2.5	A
	Efficiency	V _O = 3.3V; I _O = 1A		85		%
f _s	Switching frequency	⁽¹⁾	90	100	110	KHz
SVRR	Supply voltage ripple rejection	V _I = V _{CC} + 2V _{RMS} ; V _O = V _{ref} ; I _O = 1.A; f _{ripple} = 100Hz	60			dB
	Voltage stability of switching frequency	V _{CC} = 8 to 55V		3	6	%
	Temp. stability of switching frequency	T _J = 0 to 125°C		4		%
Reference section						
	Reference voltage		5.0	5.1	5.2	V
		I _{ref} = 0 to 10mA; ⁽¹⁾	4.950	5.1	5.250	V
		V _{CC} = 8 to 55V				
	Line regulation	I _{ref} = 0mA;		5	10	mV
		V _{CC} = 8 to 55V				
	Load regulation	V _{ref} = 0 to 5mA;		2	10	mV
		V _{CC} = 0 to 20mA		6	25	mV
	Short circuit current		30	65	100	mA

Table 5. Electrical characteristics (continued)

(T_J = 25°C, C_{OSC} = 2.7nF, R_{OSC} = 20kΩ, V_{CC} = 24V, unless otherwise specified.)

Symbol	Parameter	Test condition	Min	Typ	Max	Unit
DC Characteristics						
I _{QOP}	Total operating quiescent current			4	6	mA
I _Q	Quiescent current	Duty Cycle = 0; V _{FB} = 3.8V		2.5	3.5	mA
Error Amplifier						
V _{FB}	Voltage feedback input		3.33	3.36	3.39	V
R _L	Line regulation	V _{CC} = 8 to 55V		5	10	mV
	Ref. voltage stability vs temperature	(1)		0.4		mV/°C
V _{OH}	High level output voltage	V _{FB} = 2.5V	10.3			V
V _{OL}	Low level output voltage	V _{FB} = 3.8V			0.65	V
I _{O source}	Source output current	V _{comp} = 6V; V _{FB} = 2.5V	180	220		μA
I _{O sink}	Sink output current	V _{comp} = 6V; V _{FB} = 3.8V	200	300		μA
I _b	Source bias current			2	3	μA
SVRR E/A	Supply voltage ripple rejection	V _{comp} = V _{fb} ; V _{CC} = 8 to 55V	60	80		dB
	DC open loop gain	R _L = ∞	50	57		dB
gm	Transconductance	I _{comp} = -0.1 to 0.1mA V _{comp} = 6V		2.5		ms
Oscillator section						
	Ramp valley		0.78	0.85	0.92	V
	Ramp peak	V _{CC} = 8V	2	2.15	2.3	V
		V _{CC} = 55V	9	9.6	10.2	V
	Maximum duty cycle		95	97		%
	Maximum frequency	Duty cycle = 0% R _{osc} = 13kW, C _{osc} = 820pF			300	kHz

1. Specification referred to T_J from 0 to 125°C

5 Typical characteristics

Figure 4. Quiescent drain current vs. input voltage

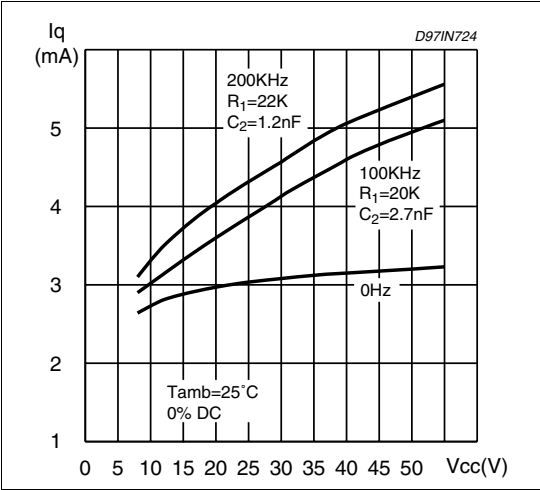


Figure 5. Line regulation

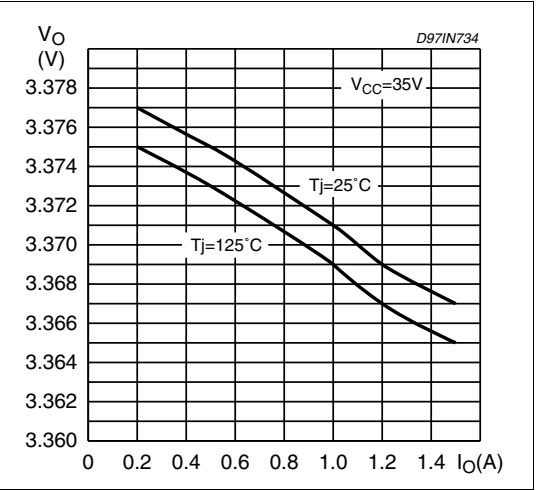


Figure 6. Quiescent current vs. junction temperature

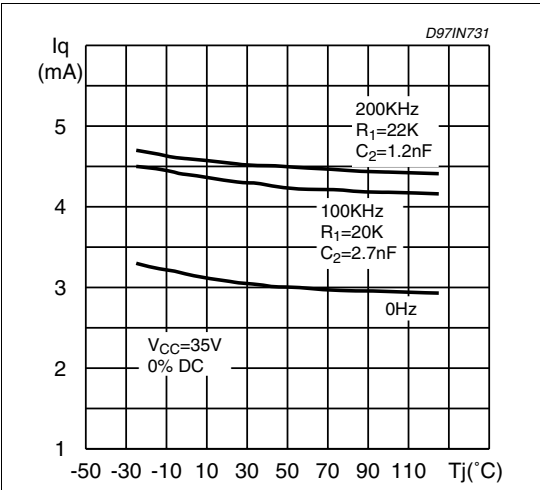


Figure 7. Switching frequency vs. R1 and C2

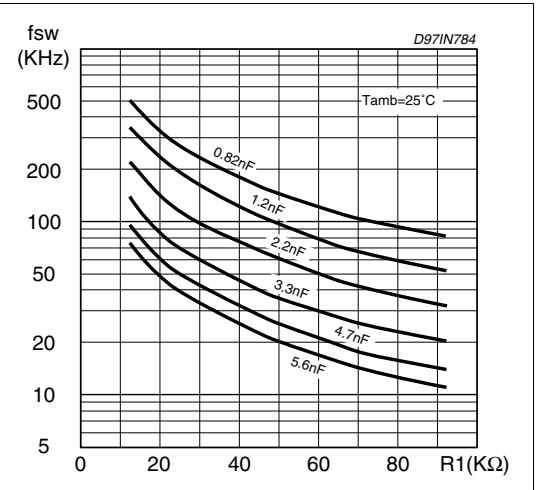


Figure 8. Load regulation

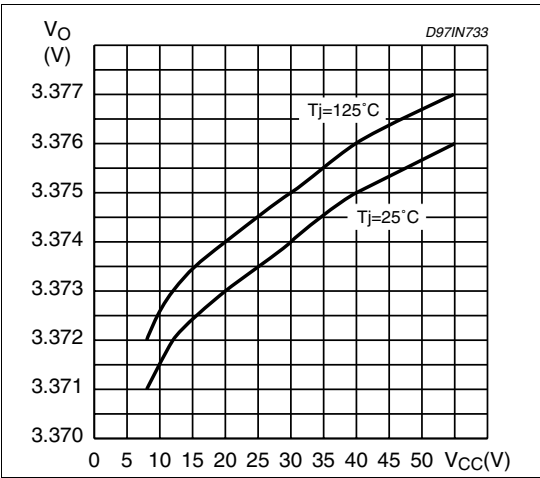


Figure 9. Switching frequency vs. input voltage

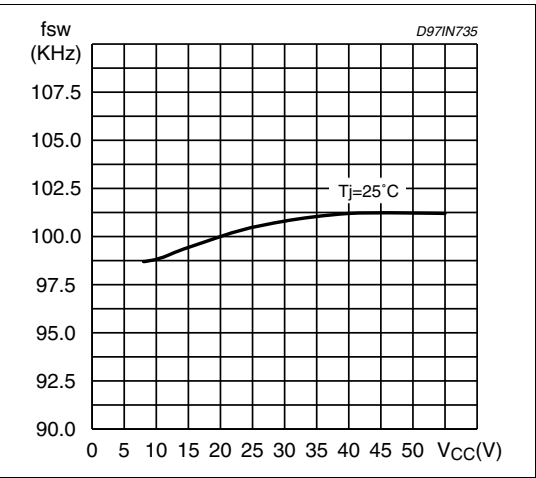


Figure 10. Switching frequency vs. junction temperature

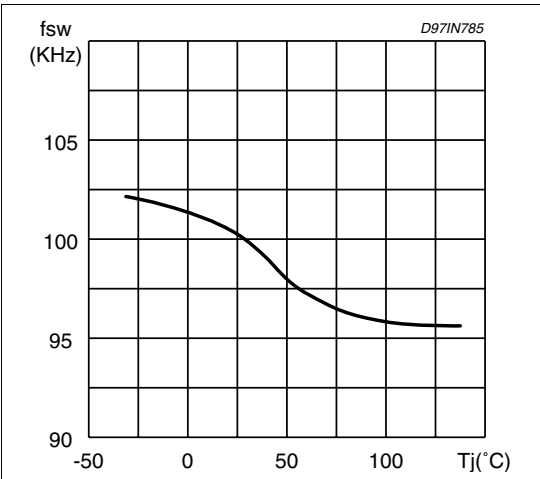


Figure 11. Efficiency vs. output current

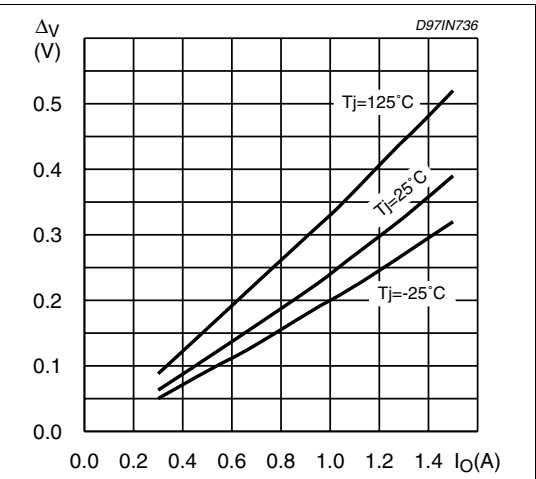


Figure 12. Dropout voltage between pin 5 and 4

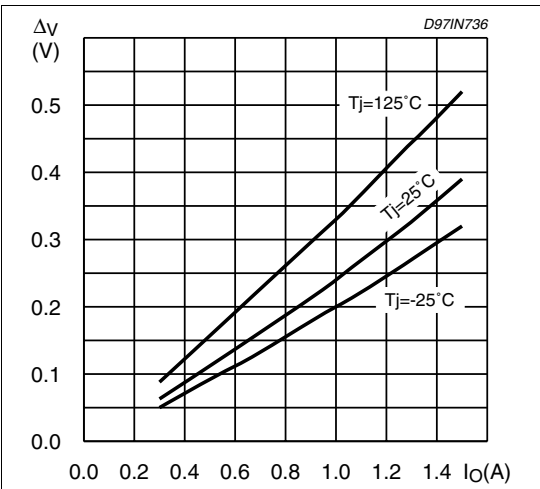


Figure 13. Efficiency vs. output current

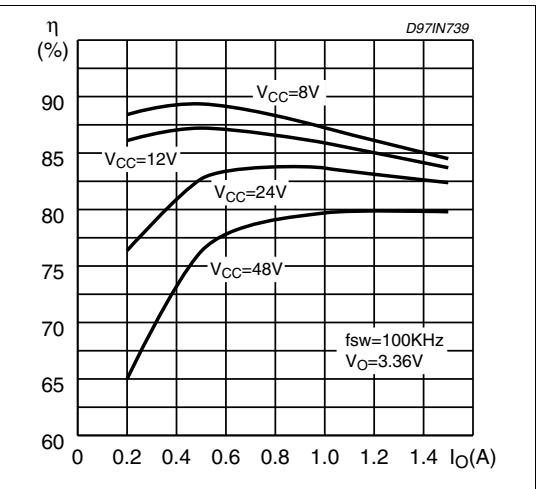


Figure 14. Efficiency vs output voltage

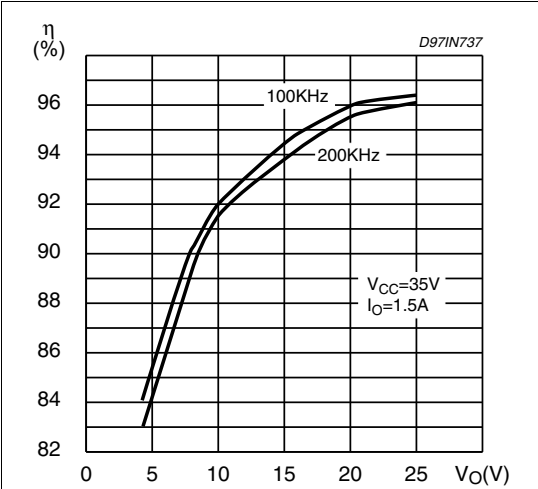


Figure 15. Efficiency vs. output current

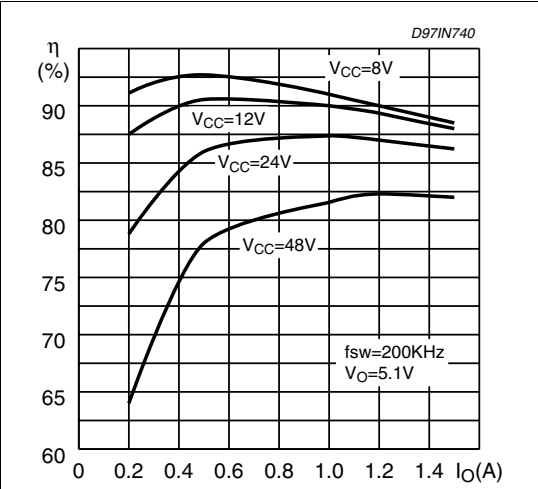


Figure 16. Efficiency vs. output current

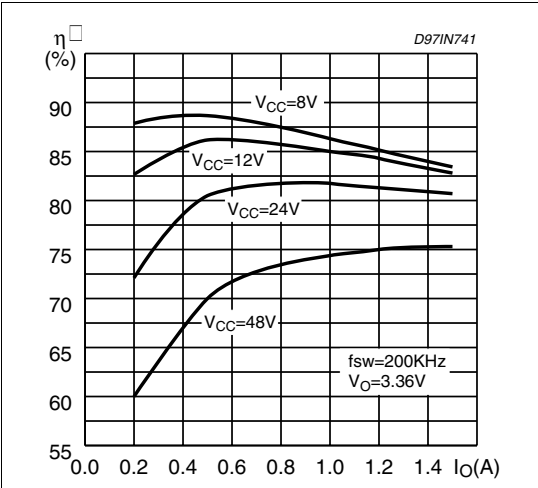


Figure 17. Efficiency vs. V_O

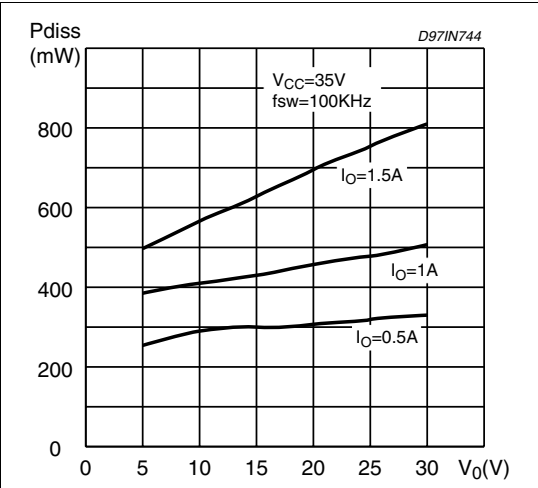


Figure 18. Efficiency vs. V_{CC}

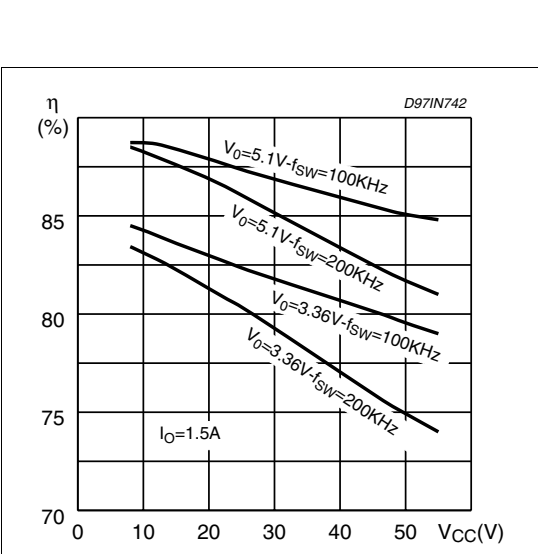


Figure 19. Pulse by pulse limiting current vs. junction temperature.

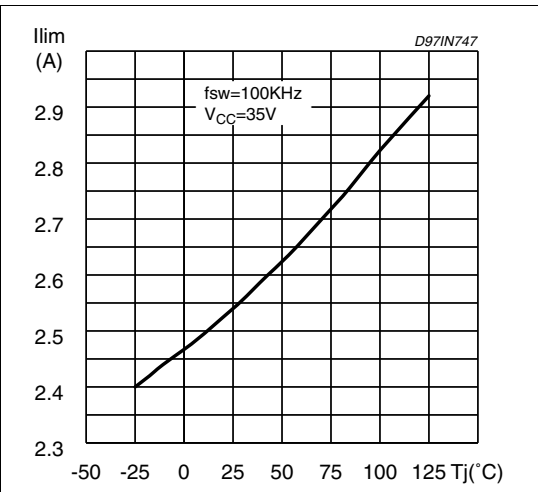


Figure 20. Power dissipation vs. V_{CC}

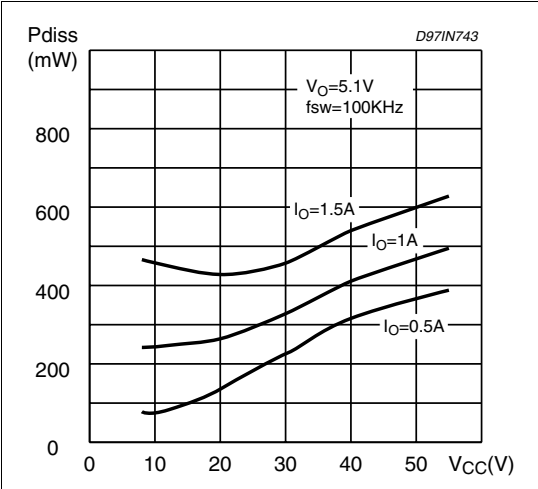


Figure 21. Load transient

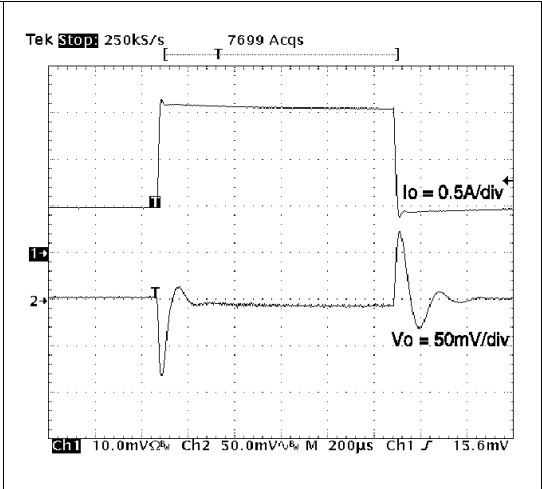


Figure 22. Line transient

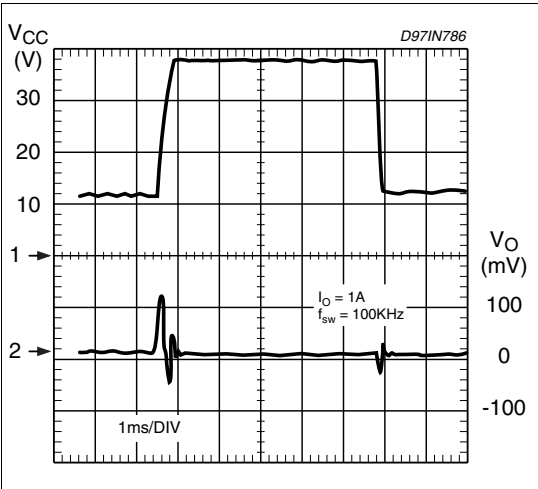
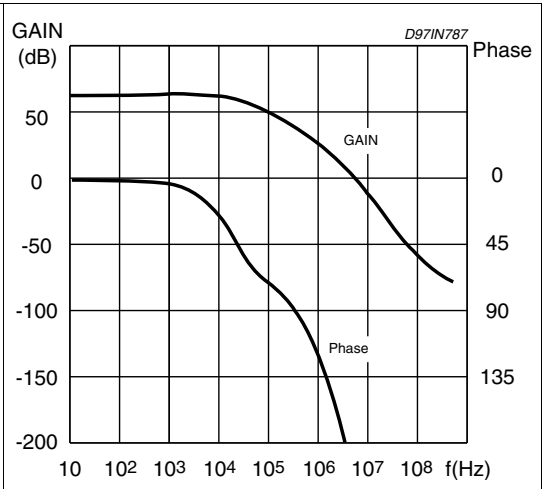


Figure 23. Open loop frequency and phase of error amplifier



6 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

Figure 24. DIP8 mechanical data & package dimensions

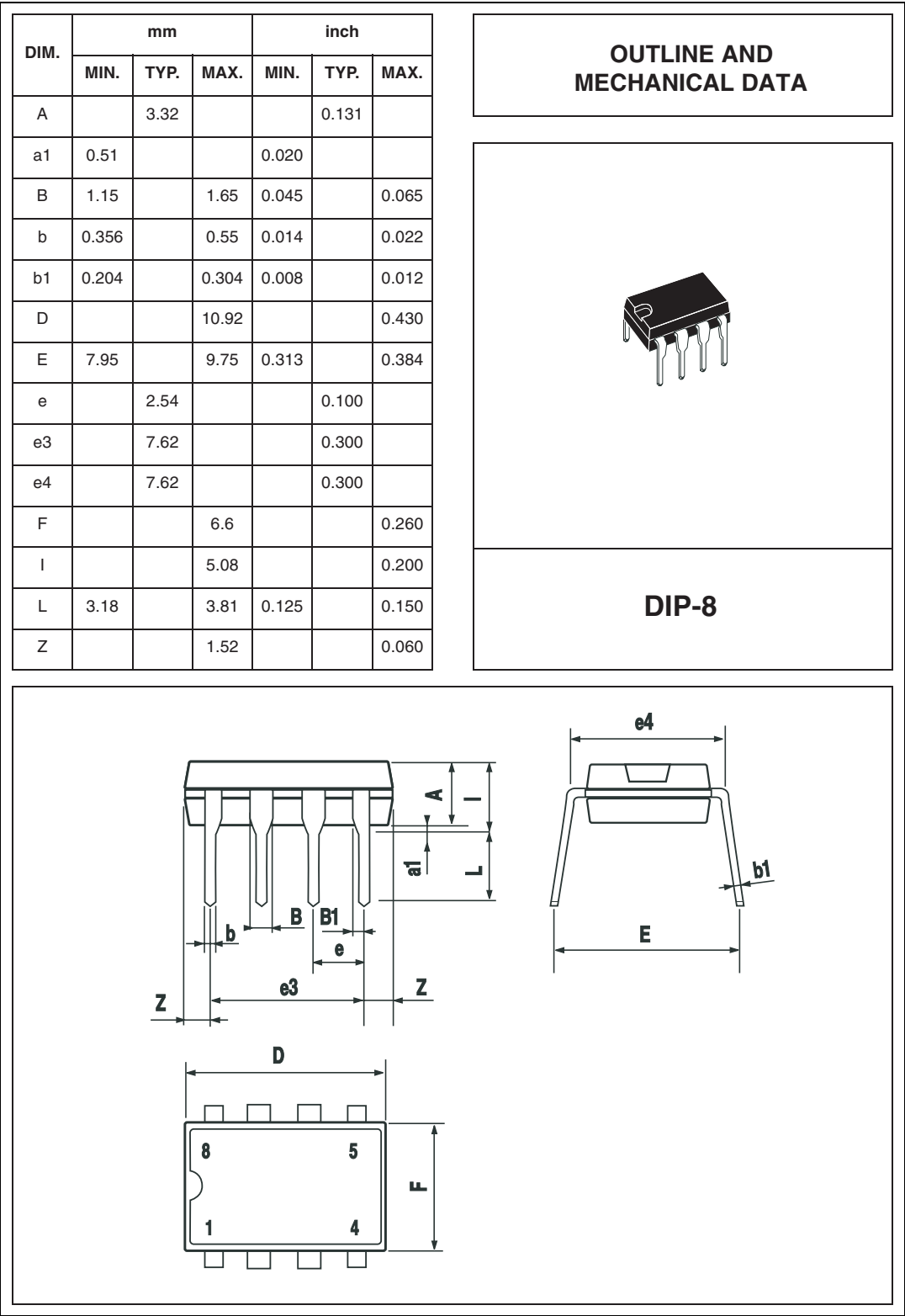
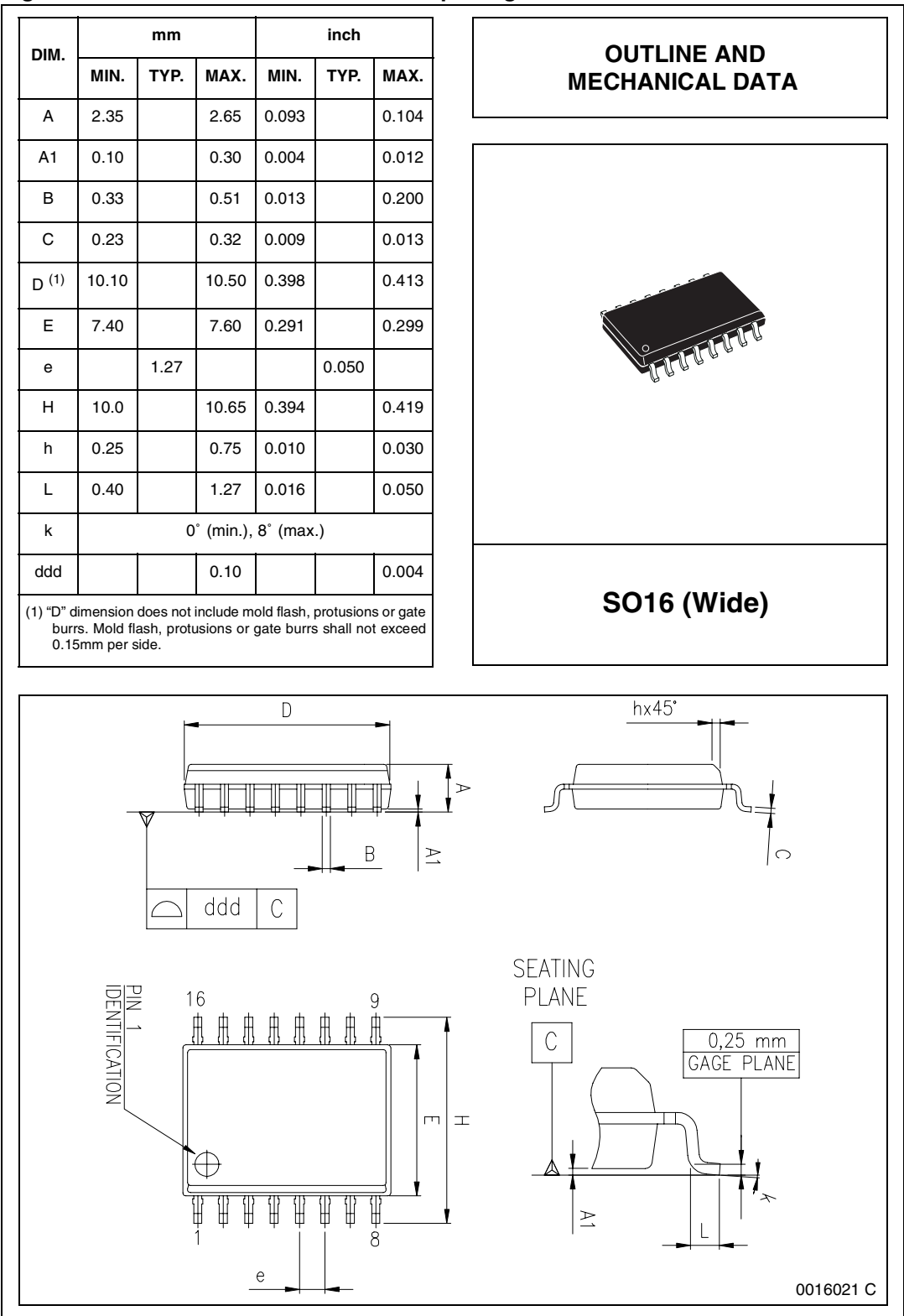


Figure 25. SO16Wide mechanical data & package dimensions



7 Order code

Table 6. Order code

Part number	Package	Packaging
L4976	DIP8	Tube
L4976D	SO16W	Tube
L4976D013TR	SO16W	Tape and reel

8 Revision history

Table 7. Revision history

Date	Revision	Changes
5-Aug-2001	6	First Issue
3-Apr-2007	7	Document reformatted, updated dropout voltage values in Table 5 on page 6

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